IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Charles W. Eichelberger

rial No.: 08/650,628

Group Art Unit: 2508

ed:

05/20/96

Examiner: Potter, R.

SINGLE CHIP MODULES, REPAIRABLE MULTICHIP MODULES, AND METHODS OF FABRICATION THEREOF

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on May 0.7, 1998.

> Kevin P. Radigad Esq. Attorney for Applicant Req. No. 31,789

Date of Signature: May <u>07</u>, 1998

To: Assistant Commissioner for Patents

Washington, D.C. 20231

Response to Office Action

Dear Sir:

This paper is filed in response to the Office Action mailed January 12, 1998 in connection with the above-designated application. A request for a one-month extension of time is submitted herewith so that this paper is being timely filed. Reconsideration and allowance of all claims pending in the application are respectfully requested in view of the amendments and remarks below.